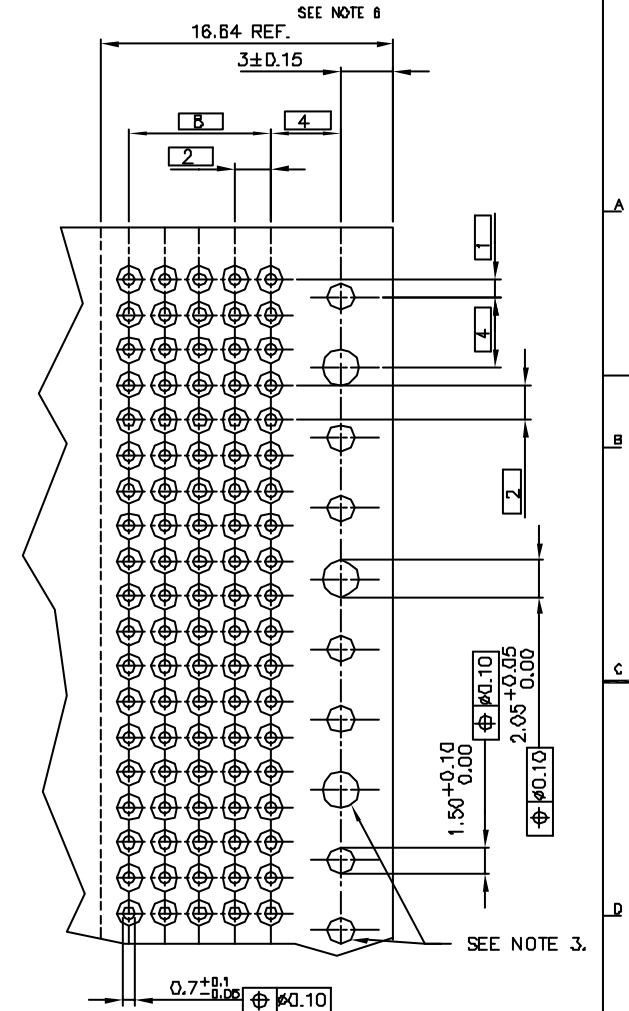
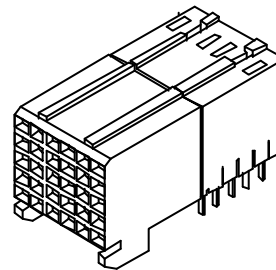
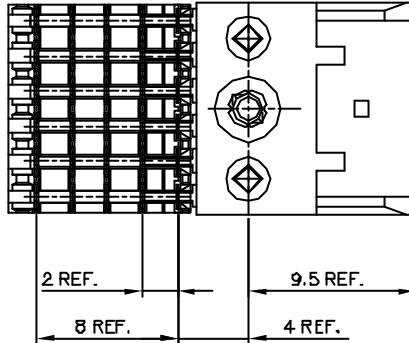
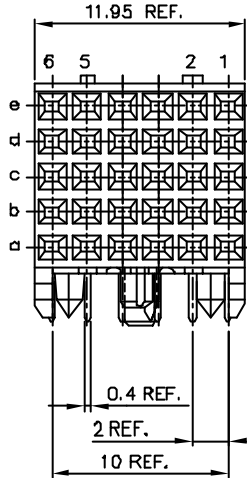
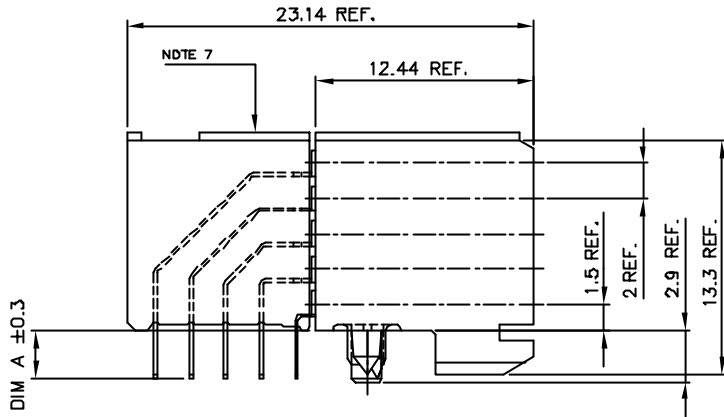


PRODUCT NR:	PLATING CONTACT AREA	UNDERPLATING
85863-1Y2/1Y2LF	0.8 μ m GOLD	1.3 μ m Ni MIN.
85863-2Y2/2Y2LF	2.0 μ m GOLD	1.3 μ m Ni MIN.
85863-3Y2/3Y2LF	1.3 μ m GOLD	1.3 μ m Ni MIN.
85863-9Y2/9Y2LF	0.8 μ m GXT	1.3 μ m Ni MIN.

PC BOARD VERSIONS		
PRODUCT NR:	PCB THICKNESS	DIM A
85863-X02/X02LF	1.6	2.73
85863-X12/X12LF	2.4	3.53



RECOMMENDED HOLE PATTERN, COMPONENT SIDE.

NOTES:

- BODY MAT'L: LIQUID CRYSTAL POLYMER 30% GLASS
FLAME RETARDANT ACC. UL 94-V0
- TERMINAL MATERIAL: PHOSPHOR BRONZE.
- INDICATED HOLES ARE UNPLATED.
- PLATING SOLDER TAILS 2-8 μ m SnPb 90-97 OR 2-8 μ m PURE Sn
- PRODUCT MARKING: PART NUMBER & BATCH ID.
- SET BACK FOR TAIL BLOCK
- TOP SURFACE OF PRESS BLOCK MAY EXTEND UP TO 0.4MM HIGHER THAN HOUSING. THIS MAY AFFECT THE TAIL LENGTH BEFORE APPLICATION TO A BOARD.
- THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- THE HOUSING WILL WITHSTAND EXPOSURE TO 260 DEGREE PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION.

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PC BOARD THICKNESS A 0.2 (SEE TABLE)

mat'l code		tolerances unless otherwise specified		CUSTOMER		ELECTRONICS	
SEE NOTE				GDPR		F41	
tr	rev no of date	linear		projection	5	ROW R.A. S.T.B. SIGNAL	
A	H40627 RW 041005					RECEPT, 12 mm MOD.PP	
B	V00678 UA 020318	angles				product SERIAL (Lm)	code
C	V00860 NY 020612	dr	R. VISSCHERS 041005	mm		size	213
D	0504-0104 GU 041222	eng	E. FEUEN 041005	scale	B:1	A2	85863
		chr	E. FEUEN 041005				sheet
		appl	E. FEUEN 041005				1 of 1
sheet index	revision sheet	D					
	1						